

OK TO ENTER: /D.G./

AMENDMENT UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP 2894
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2894

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE METHOD OF
MANUFACTURING

AMENDMENT UNDER 37 C.F.R. § 1.116

MAIL STOP AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated October 10, 2008, please amend the above-identified application as follows on the accompanying pages.

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AMENDMENTS TO THE CLAIMS

REMARKS